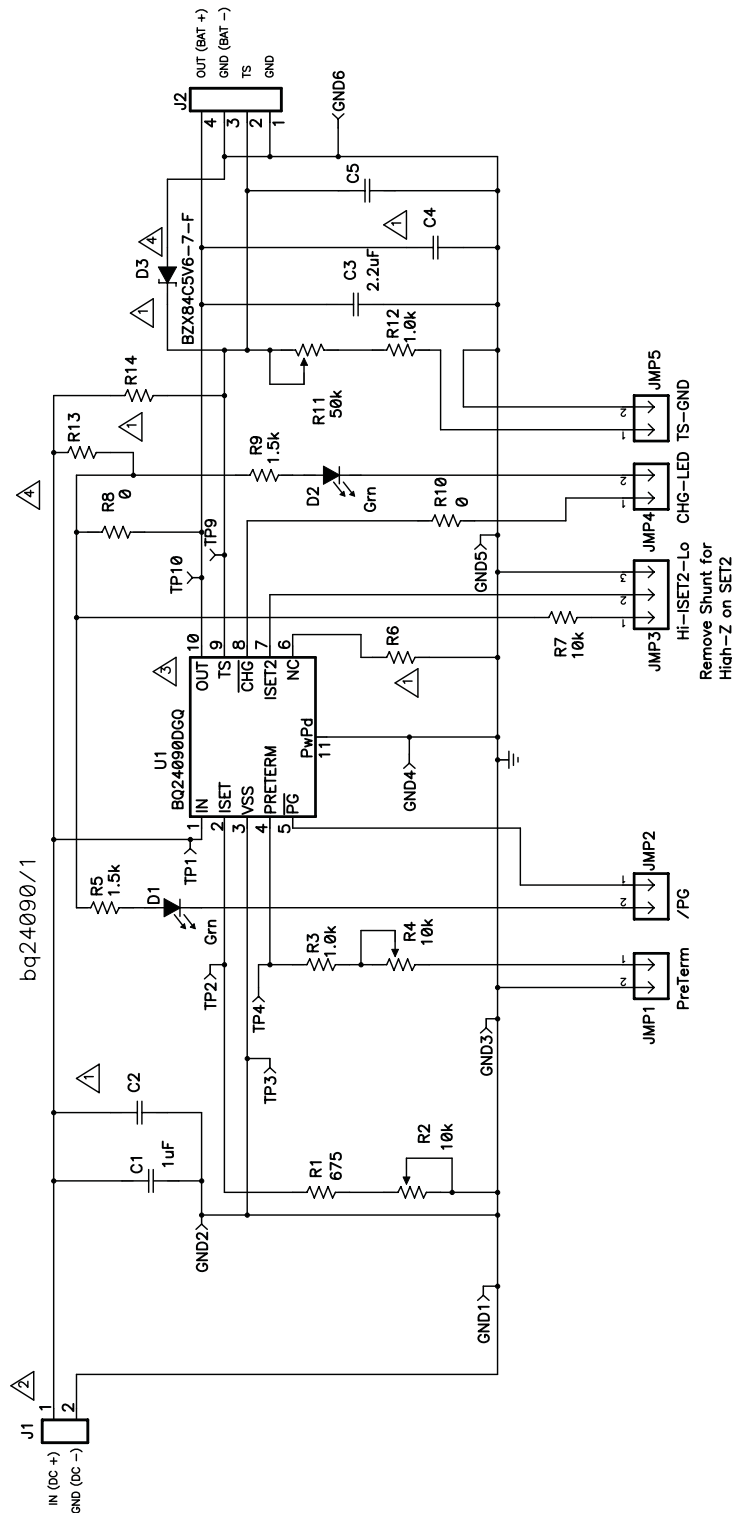


5 Schematic, Physical Layouts and Bill of Materials

5.1 Schematic



⚠ Do not install D3, R6, R13 & R14. C2, C4 and C5 are not installed and can be used for additional capacitance if desired.

⚠ R14 may be used in a future development.

⚠ Input Voltage: 4.5V to 5.5VDC Typical, Consider Thermal Issues for > 5.5V to OVP; No charging above OVP.

⚠ OUT is a 4.2V regulated output with a programmable output current of 1A maximum.

⚠ TP1 → TP10 are associated with U1 pin out. TP5,6,7 & 8 are omitted.

⚠ R8 connects OUTpin pull-up for the LEDs and ISET2. Can move R8 to R13 if Vin is desired as the pull-up source (note Vin should be <7V for this configuration or clamp voltage with D3, if R14 is installed).

Figure 2. bq24090/1/2/3 EVM Board Schematic

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